

ABSTRACT

Providing a method for manufacturing a multilayer wiring board and a touch panel, which does not cause decreasing of yields, reliabilities and productivities even though the 5 materials of each board to be stacked are different, and which manufactures the multilayer wiring board and the touch panel at low cost with high productivities. A multilayer wired board constituting at least part of a electrical circuit board in which a plurality of wired boards are stacked so as to face 10 their wired surfaces each other, wherein: electrical connection parts between the multilayer wired boards are connected through an elastic conductive material part adhered to one of the wired boards; and at least part of a peripheral edge portion of the elastic conductive material part is adhered 15 by a double-sided adhesive material part to seal the plurality of multilayer wired boards.